

2.4.1.3. Financials.**Table 2.2. Amkor financial results for 2002 and 2003.**

	2003	2002
Net revenue (\$millions)	\$1,604	\$1,406
Cost of goods sold (\$millions)	\$1,267	\$1,311
Gross margin (\$millions)	\$336	\$96
Gross margin (%)	20.9%	6.8%
Operating expenses (\$millions)	\$213	\$513
Operating incomes (\$millions)	\$123	(\$417)
Operating income (%)	7.7%	(29.7%)
Net Income (\$millions)	\$2	(\$827)
Cash and cash equivalents (\$millions)	\$313	\$311

Note that the financial results in table 2.2 do not include any revenue for 2002 for Amkor's wafer fabrication business that was sold in Q1 of 2003 for \$62 millions dollars.

Amkor's 2003 financial result show very strong improvement over 2002 and Amkor appear well positioned for the upturn that is gathering steam as this report is being written with sufficient cash on-hand to make any necessary capital investments.

2.4.1.4. Manufacturing facilities

Amkor has over four million square feet of factory manufacturing space with 10 factories located throughout asia, see table 2.3.

Table 2.3. Amkor factories.

Location	Factory	Square footage	Commenced operations	Products
South Korea	K1	670,000	1968	Packaging and test services, packaging and process development.
South Korea	K3	428,000	1994	Packaging services and back grind
South Korea	K4	1,100,000	1996	Packaging and test services
Philippines	P1	602,000	1989	Packaging and test service. Packaging and process development.
Philippines	P2	112,000	1993	Packaging services
Philippines	P3	406,000	1995	Packaging and test services
Philippines	P4	219,000	2000	Test services
Japan	J1	147,000	2001	Packaging and test services
Taiwan	T1	275,000	2001	Packaging and test services
China	C1	150,000	2001	Manufacturing (Turnkey: probe assembly and test), R&D and distribution

Note: Japan facility is a joint venture with Toshiba (AIC - Amkor Iwate Company)

2.4.1.5. Services

- Packages: stacked chip scale packages, wafer level packaging, small form factor memory cards, system in package modules, image sensor packaging, laminate packages including BGA, Flip Chip and PGA, tape pack-